

Title (en)

Polishing pad and method of polishing a semiconductor wafer

Title (de)

Schleifkissen und Verfahren zum Polieren einer Halbleiterplatte

Title (fr)

Tampon de polissage et procédé de polissage d'une plaquette de semi-conductrice

Publication

EP 1470892 A1 20041027 (EN)

Application

EP 04009441 A 20040421

Priority

JP 2003117538 A 20030422

Abstract (en)

A polishing pad (1) comprises a polishing substrate (11) having a through-hole extending from its polishing surface to the opposite surface, and a light-transmitting member (2) arranged in the through hole. The light-transmitting member is fixed in the through-hole by bonding its outer wall to the inner wall of through-hole with a photocured adhesive layer (3). Independent claims are also included for: (1) a polishing pad laminate comprising the above polishing pad, and a base layer having light transmission properties formed on the surface opposite to the polishing surface of polishing pad; and (2) a method of polishing a semiconductor wafer with the above polishing pad or polishing pad laminate, where the polishing end point of semiconductor wafer is detected by an optical end-point detection device through the light transmitting member of polishing pad or polishing pad laminate.

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IPC 8 full level

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Citation (search report)

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